

### DESCRIPTION

The IS2805 is an optically coupled isolator consists of two infrared emitting diodes in reverse parallel connection and optically coupled to an NPN silicon photo transistor.

This device belongs to Isocom Compact Range of Optocouplers.

# **FEATURES**

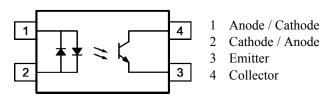
- Half Pitch 1.27mm
- High AC Isolation voltage 3750V<sub>RMS</sub> .
- Wide Operating Temperature Range -55°C to 100°C
- Pb Free and RoHS Compliant
- UL Approval E91231, Model AHP

### APPLICATIONS

- **Ring Detection on Telephone Lines**
- Industrial System Controllers
- **Measuring Instruments**
- Signal Transmission between Systems of **Different Potentials and Impedances**

### **ORDER INFORMATION**

Available in Tape and Reel with 1000pcs per reel



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^{\circ}C$ )

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

#### Input

Forward Current	±50mA
Peak Forward Current (t=10µs)	±1A
Power Dissipation No Derating required up to $T_A = 100^{\circ}C$	70mW
Output	

Collector to Emitter Voltage $V_{CEO}$	80V
Emitter to Collector Voltage $V_{\text{ECO}}$	6V
Power Dissipation	150mW
Power Dissipation Derating Factor (above T <sub>A</sub> = 80°C)	3.7mW/°C

### Total Package

Isolation Voltage	$3750V_{\text{RMS}}$
Total Power Dissipation	200mW
Operating Temperature	-55 to 100 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

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# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise specified)

#### INPUT

Parameter	Symbol	Test Condition	Min	*Typ.	Max	Unit
Forward Voltage	$V_{\rm F}$	$I_F = \pm 20 mA$		1.2	1.4	V
Terminal Capacitance	C <sub>IN</sub>	V = 0V, f = 1KHz		50	250	pF

#### OUTPUT

Parameter	Symbol	Test Condition	Min	*Typ.	Max	Unit
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	$I_{\rm C} = 0.1 {\rm mA},  I_{\rm F} = 0 {\rm mA}$	80			V
Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	$I_E = 0.01 \text{mA}, I_F = 0 \text{mA}$	6			V
Collector-Emitter Dark Current	I <sub>CEO</sub>	$V_{CE} = 20V, I_F = 0mA$			100	nA

#### COUPLED

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current Transfer Ratio	CTR	$I_F = \pm 1 \text{mA}, V_{CE} = 5 \text{V}$	20		300	%
CTR Symmetry		$I_F = \pm 1 \text{mA}, V_{CE} = 5 \text{V}$	0.5		2.0	
Collector – Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_F = \pm 20 \text{mA}, I_C = 1 \text{mA}$		0.1	0.2	V
Floating Capacitance	$C_{\rm f}$	V = 0V, f = 1MHz		0.6	1.0	pF
Output Rise Time	t <sub>r</sub>	$V_{CE} = 2V,$			18	μs
Output Fall Time	t <sub>f</sub>	$Ic = 2mA, R_L = 100\Omega$			18	

#### ISOLATION

Parameter	Symbol	Test Condition	Min	*Typ.	Max	Unit
Input to Output Isolation Voltage	V <sub>ISO</sub>	AC 1 minute, RH = 40% to 60% Note 1	3750			V <sub>RMS</sub>
Input to Output Isolation Resistance	R <sub>ISO</sub>	$V_{IO}$ = 500V, RH = 40% to 60% Note 1	5x10 <sup>10</sup>	1x10 <sup>11</sup>		Ω

Note 1 : Measured with input leads shorted together and output leads shorted together, R.H 40% to 60%

\* : Typical Values at  $T_A = 25^{\circ}C$ 



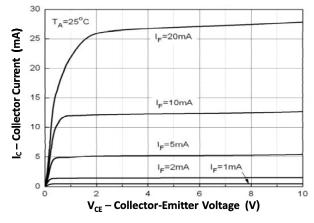


Fig 1 Collector Current vs Collector-Emitter Voltage
(1)

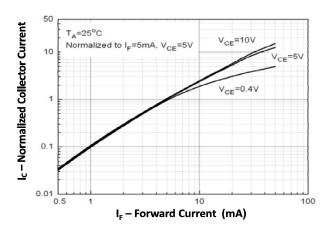
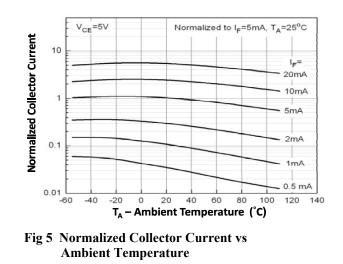
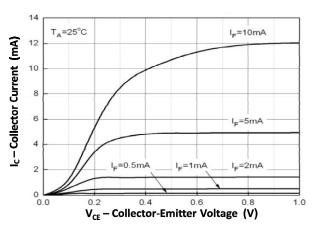
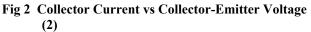


Fig 3 Normalized Collector Current vs Forward Current







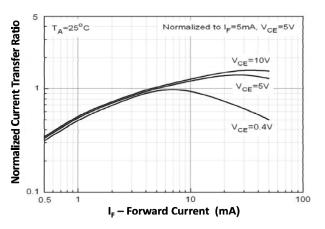


Fig 4 Normalized Current Transfer Ratio vs Forward Current

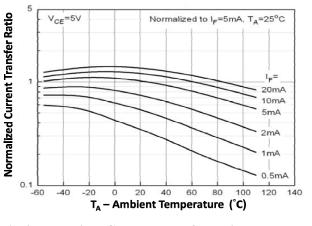
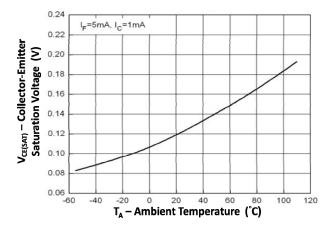
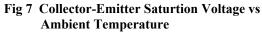


Fig 6 Normalized Current Transfer Ratio vs Ambient Temperature







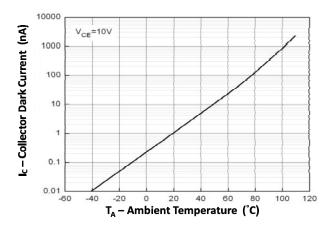
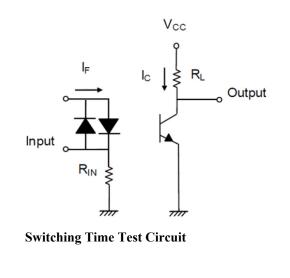
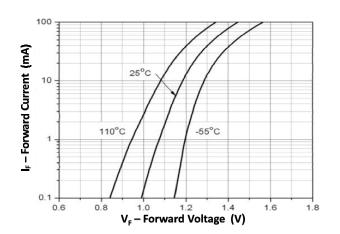
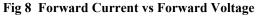


Fig 9 Collector Dark Current vs Ambient Temperature







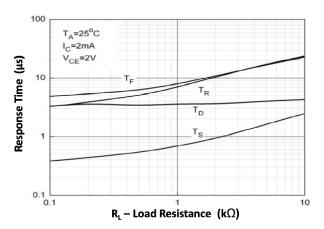
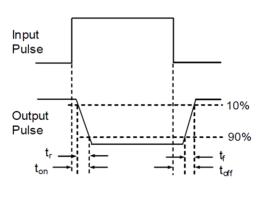


Fig 10 Response Time vs Load Resistance





### ORDER INFORMATION

IS2805			
After PN	PN	Description	Packing quantity
None	IS2805	Surface Mount Tape & Reel	1000 pcs per reel

### **DEVICE MARKING**

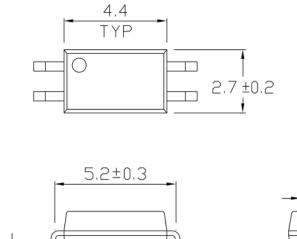


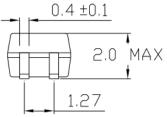
AHP1 0	lenotes Device Part Number
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- I denotes Isocom
- Y denotes 1 digit Year code
- WW denotes 2 digit Week code



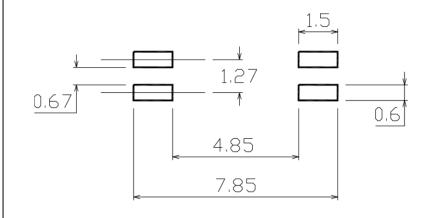
# PACKAGE DIMENSIONS (mm)





# **RECOMMENDED SOLDER PAD LAYOUT (mm)**

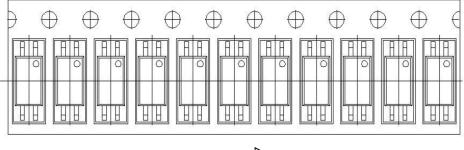
7 ±0.3



0.2

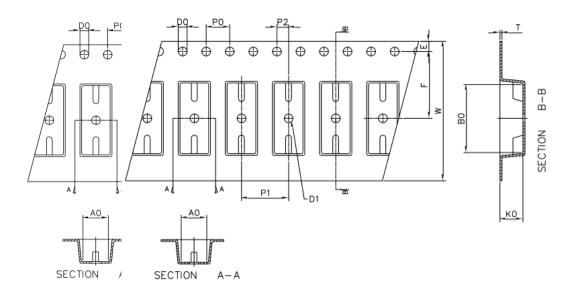


# TAPE AND REEL PACKAGING





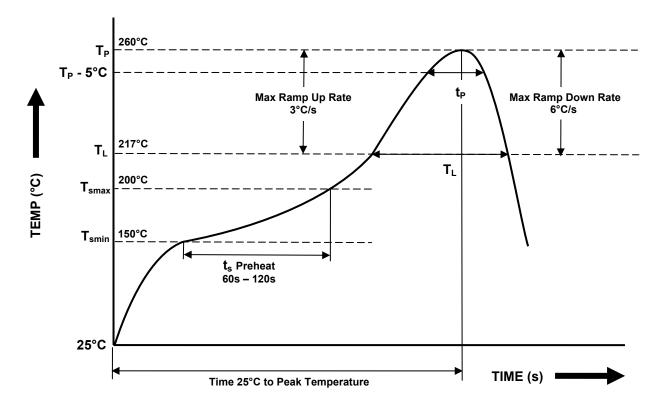
Direction of Feed from Reel



Dimension No.	A0	В0	D0	D1	E	F
Dimension( mm)	3.00±0.10	7.45±0.10	1.50+0.1/-0	1.50±0.10	1.75±0.10	5.5±0.10
Dimension No.	P0	P1	P2	t	W	К0
Dimension (mm)	4.00±0.15	4.00±0.10	2.00±0.10	0.30±0.05	12.1±0.2	2.45±0.1



### IR REFLOW SOLDERING TEMPERATURE PROFILE One Time Reflow Soldering is Recommended. Do not immerse device body in solder paste.



Profile Details	Conditions
Preheat - Min Temperature (T <sub>SMIN</sub> ) - Max Temperature (T <sub>SMAX</sub> ) - Time T <sub>SMIN</sub> to T <sub>SMAX</sub> (t <sub>s</sub> )	150°C 200°C 60s - 120s
$\label{eq:solution} \begin{array}{l} \textbf{Soldering Zone} \\ & - \mbox{Peak Temperature} (T_{P}) \\ & - \mbox{Liquidous Temperature} (T_{L}) \\ & - \mbox{Time within 5°C of Actual Peak Temperature} (T_{P}-5°C) \\ & - \mbox{Time maintained above } T_{L} (t_{L}) \\ & - \mbox{Ramp Up Rate} (T_{L} \mbox{ to } T_{P}) \\ & - \mbox{Ramp Down Rate} (T_{P} \mbox{ to } T_{L}) \end{array}$	260°C 217°C 30s 60s 3°C/s max 6°C/s max
Average Ramp Up Rate ( $T_{smax}$ to $T_P$ )	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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